



HIGH-DENSITY ARRAY CABLE SYSTEMS

SEARAY™ 0.80 mm & 1.27 mm PITCH ASSEMBLIES

0.80 mm Pitch SEARAY™ Cable Assembly

- 0.80 mm (.0315") pitch for 2x the density of SEARAY™ 1.27 mm pitch
- Up to 300 I/Os (1/4 of pins are dedicated to ground)
- 8 and 10 row designs
- 34 AWG micro ribbon coax cable
- 50 Ω single-ended signal routing
- Available with screw downs
- Terminal and socket end options
- Vertical and right-angle board level mates

1.27 mm Pitch SEARAY™ Cable Assembly

- 1.27 mm (.050") pitch
- Up to 500 I/Os (1/2 of pins are dedicated to ground)
- 4, 6, 8 and 10 row designs
- Choice of 36 AWG 50 Ω micro coax or 32 AWG 100 Ω twinax cable
- Positive latching when mated
- Supports PCIe® Gen 2 and Gen 3 protocols
- Optional top latch for space savings
- Guide posts available for more rugged applications
- Vertical, right-angle and press-fit board level mates



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0.80 mm Pitch System

- ESCA – Ultra-High Density Array Cable Assembly
- SEAM8 – Ultra-High Density Array, Terminal
- SEAF8 – Ultra-High Density Array, Socket
- SEAF8-RA – Right-Angle Array, Socket

1.27 mm Pitch System

- SEAC – High-Speed, High-Density Array Cable Assembly
- SEAF – High-Speed, High-Density Array, Socket
- SEAFP – Press-Fit Array, Socket
- SEAFP-RA – Press-Fit Right-Angle Array, Socket

For more High-Speed Cable and High-Density Array solutions, please visit www.samtec.com/cable and www.samtec.com/arrays